

Buildup for Mindteck
mind-19jul2k11-11768

0.0350	copper plating layer 1		
0.0175	copper foil layer1	Signal	6.5 mil traces 6 mil seperation 94.63 ohms differential Target 100 ohms
0.1500	Prepreg 1-2		
0.0350	copper foil layer 2	Plane	
0.2000	Core 2-3		
0.0350	copper foil layer 3	Signal	6 mil traces 12.3 mil seperation 109.03 ohms differential Target 100 ohms
0.1500	Prepreg 3-4		
0.0350	copper foil layer 4	Signal	6 mil traces 12.3 mil seperation 109.03 ohms differential Target 100 ohms
0.2000	Core 4-5		
0.0350	copper foil layer 5	Plane	
0.1500	Prepreg 5-6		
0.0350	copper foil layer 6	Signal	5 mil traces 20 mil seperation 107.10 ohms differential Target 100 ohms
0.2000	core 6-7		
0.0350	copper foil layer 7	Plane	
0.1500	prepreg 7-8		
0.0175	copper foil layer 8	Signal	6.5 mil traces 6 mil seperation 94.63 ohms differential Target 100 ohms
0.0350	copper plating layer 8		
1.5150	total pcb thickness in mm		

Disclaimer: This stack-up has assumptions regarding the copper area per layer, as well as prepreg distance & dielectric constants. An impedance tolerance of +/- 10% can only be achieved if we adjust the trace width & prepreg height to meet the impedance requirement after receipt of the gerber files.